

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3678	438/106.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:37
L2	1392	438/107.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:37
L3	1214	438/125.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:37
L4	853	438/129.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:37
L5	1625	438/613.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:37
L6	209	438/599.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:37
L7	346	438/598.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:37
L8	2492	257/723.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:37

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L9	2422	257/737.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:40
L10	2502	257/676.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:37
L11	1492	438/123.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:37
L12	1625	438/613.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:37
L13	1492	438/123.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:37
L14	15755	L1 L2 L3 L4 L5 L6 L7 L8 L9 L10 L11 L12 L13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:37
L15	159	(L14 and ((cavity or void or opening or pocket) with (carrier or wafer or substrate or pcb or board)))and @pd>"20060904"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:42
L16	20	257/750.ccls. and @pd>"20060904"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/15 17:38

EAST Search History

L17	2388	((plurality or multiple or numerous) with (chip or die or ic or (integrated adj circuit) or semiconductor)) and (via) and (trace or line or lead) and ((carrier or wafer or board or pcb) with (scribe or scribing or dice or dicing)) and (solder or bump) and ((ceramic or silicone or glass or si or silicon or plastic) with (carrier or wafer or pcb or board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:38
L19	90	(L17 and (polyimide or BCB)) and @pd>"20060904"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:41
L20	1239	257/e21.499.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:40
L21	83	257/e21.5.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:40
L22	1691	257/e21.502.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:40
L23	2474	257/e21.503.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:40
L24	2240	257/e21.505.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:40

EAST Search History

L25	2891	257/e21.508.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:40
L26	165	(14 and (polyimide or BCB)) and @pd>"20060904"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:42
L27	8833	22 23 24 25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:42
L28	2841	(27 and (polyimide or BCB))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:42
L29	4468	(14 and (polyimide or BCB))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:42
L30	351	15 16 19 26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:43
L31	6393	28 29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:44
L32	4116	28 29	USPAT	OR	ON	2006/12/15 17:43
L33	2145	32 and die	USPAT	OR	ON	2006/12/15 17:43
L34	3810	32 and chip	USPAT	OR	ON	2006/12/15 17:43
L35	3234	32 and solder	USPAT	OR	ON	2006/12/15 17:43
L36	2433	32 and ball	USPAT	OR	ON	2006/12/15 17:43
L37	3302	32 and (plural or plurality)	USPAT	OR	ON	2006/12/15 17:44

EAST Search History

L38	5928	31 not 17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:44
L39	1778	38 not 14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:45
S1	935	257/750.ccls.	USPAT	OR	OFF	2006/03/10 19:01
S2	1390	257/750.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/04 18:38
S3	3947	(chip or die or ic or (integrated adj circuit) or semiconductor) and (via) and (trace or line or lead) and ((carrier or wafer) same (scribe or scribing or dice or dicing)) and (solder or bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 19:04
S4	3213	((plurality or multiple or numerous) with (chip or die or ic or (integrated adj circuit) or semiconductor)) and (via) and (trace or line or lead) and ((carrier or wafer) same (scribe or scribing or dice or dicing)) and (solder or bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 19:05
S5	2958	((plurality or multiple or numerous) with (chip or die or ic or (integrated adj circuit) or semiconductor)) and (via) and (trace or line or lead) and ((carrier or wafer) with (scribe or scribing or dice or dicing)) and (solder or bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 19:05
S6	1756	((plurality or multiple or numerous) with (chip or die or ic or (integrated adj circuit) or semiconductor)) and (via) and (trace or line or lead) and ((carrier or wafer) with (scribe or scribing or dice or dicing)) and (solder or bump) and ((ceramic or silicone or glass or si or silicon or plastic) with (carrier or wafer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:37

EAST Search History

S7	95	S6 and (polimide or BCB)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 19:11
S8	37	S7 and ((cu or copper or ni or nickel) with (line or lead or trace))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 19:07
S9	1783	((plurality or multiple or numerous) with (chip or die or ic or (integrated adj circuit) or semiconductor)) and (via) and (trace or line or lead) and ((carrier or wafer or board or pcb) with (scribe or scribing or dice or dicing)) and (solder or bump) and ((ceramic or silicone or glass or si or silicon or plastic) with (carrier or wafer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 19:17
S10	2060	((plurality or multiple or numerous) with (chip or die or ic or (integrated adj circuit) or semiconductor)) and (via) and (trace or line or lead) and ((carrier or wafer or board or pcb) with (scribe or scribing or dice or dicing)) and (solder or bump) and ((ceramic or silicone or glass or si or silicon or plastic) with (carrier or wafer or pcb or board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 19:10
S11	109	S10 and (polimide or BCB)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:40
S12	72	S11 not S8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 19:11

EAST Search History

S13	809	((plurality or multiple or numerous) with (chip or die or ic or (integrated adj circuit) or semiconductor)) and (via) and (trace or line or lead) and ((carrier or wafer or board or pcb) with (scribe or scribing or dice or dicing)) and (solder or bump) and ((cavity or void or opening or pocket) with (carrier or wafer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 12:12
S14	779	S13 not S12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 19:18
S15	765	S13 not S11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 20:18
S21	969	(chip or die or ic or (integrated adj circuit) or semiconductor) and (via) and (trace or line or lead) and ((carrier or wafer or board or pcb) with (scribe or scribing or dice or dicing)) and (solder or bump) and ((cavity or void or opening or pocket) with (carrier or wafer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 12:12
S22	160	S21 not S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 20:29
S24	2177	257/737.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 12:11
S25	2360	257/676.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 20:30

EAST Search History

S26	1368	438/123.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 20:30
S27	1463	438/613.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 20:43
S28	1368	438/123.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 20:44
S29	459	438/110.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 20:44
S30	1039	438/113.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 11:52
S31	1371	S29 S30	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 20:44
S32	1307	S31 not S21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/10 20:44
S33	3362	438/106.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 11:52

EAST Search History

S34	1270	438/107.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 11:52
S35	1105	438/125.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 11:52
S36	814	438/129.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 11:53
S37	1463	438/613.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 12:00
S38	199	438/599.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 11:53
S39	321	438/598.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 11:53
S40	1	("6709897").PN.	USPAT	OR	OFF	2006/03/11 12:00
S41	1	"6274391".PN.	USPAT; USOCR	OR	OFF	2006/03/11 12:09
S42	2306	257/723.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 15:23

EAST Search History

S43	2177	257/737.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 12:12
S44	2360	257/676.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 12:12
S45	1368	438/123.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 12:12
S46	1463	438/613.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 12:12
S47	1368	438/123.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 12:12
S48	14496	S33 S34 S35 S36 S37 S38 S39 S42 S43 S44 S45 S46 S47	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 12:12
S49	6687	S48 and (cavity or void or opening or pocket)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 12:12
S50	3476	S48 and ((cavity or void or opening or pocket) with (carrier or wafer or substrate or pcb or board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:39

EAST Search History

S51	969	(chip or die or ic or (integrated adj circuit) or semiconductor) and (via) and (trace or line or lead) and ((carrier or wafer or board or pcb) with (scribe or scribing or dice or dicing)) and (solder or bump) and ((cavity or void or opening or pocket) with (carrier or wafer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:40
S52	3246	S50 not S51	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 12:14
S53	459	438/110.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 12:14
S54	1039	438/113.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 12:14
S55	1371	S53 S54	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 12:14
S56	3096	S52 not S55	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 12:49
S57	2044	S52 not S55	USPAT	OR	ON	2006/03/11 12:14
S58	1052	S52 not S55	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/11 12:49
S59	1	("6825553").PN.	USPAT	OR	OFF	2006/03/14 13:03
S60	1	("6964881").PN.	USPAT	OR	OFF	2006/03/14 13:04

EAST Search History

S61	228	"257"/\$6.ccls. and (trace with ((copper or cu) and (nickel or ni)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 16:48
S62	2	"257"/\$6.ccls. and ((carrier with cavity) with (mold\$3 and milling))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 16:51
S63	2	"438"/\$6.ccls. and (((carrier or substrate) with cavity) with (mold\$3 and milling))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 17:06
S64	4	"257"/\$6.ccls. and (((carrier or substrate) with cavity) with (mold\$3 and milling))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 16:54
S65	11	"257"/\$6.ccls. and (((carrier or substrate) same cavity) same (mold\$3 and milling))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 16:56
S66	1	("6548895").PN.	USPAT	OR	OFF	2006/03/14 16:56
S67	476	"438"/\$6.ccls. and (((polyimide) same via) same (ion etching))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 17:08
S68	79	"438"/\$6.ccls. and (((polyimide) with via) with (ion etching))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 17:10
S69	8	"438"/\$6.ccls. and (((polyimide) with via) with (ion adj etching))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 17:10
S70	1	("6825553").PN.	USPAT	OR	OFF	2006/09/04 18:24

EAST Search History

S71	142	(((plurality or multiple or numerous) with (chip or die or ic or (integrated adj circuit) or semiconductor)) and (via) and (trace or line or lead) and ((carrier or wafer) with (scribe or scribing or dice or dicing)) and (solder or bump) and ((ceramic or silicone or glass or si or silicon or plastic) with (carrier or wafer))) and @pd>"20060310"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:38
S72	49	257/750.ccls. and @pd>"20060310"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/15 17:38
S73	3564	438/106.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:39
S74	1347	438/107.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:39
S75	1175	438/125.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:39
S76	839	438/129.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:39
S77	1565	438/613.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:39

EAST Search History

S78	207	438/599.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:39
S79	333	438/598.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:39
S80	2420	257/723.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:39
S81	2335	257/737.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:39
S82	2454	257/676.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:39
S83	1442	438/123.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:39
S84	1565	438/613.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:39
S85	1442	438/123.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:39

EAST Search History

S86	15292	S73 S74 S75 S76 S77 S78 S79 S80 S81 S82 S83 S84 S85	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:39
S87	267	(S86 and ((cavity or void or opening or pocket) with (carrier or wafer or substrate or pcb or board)))and @pd>"20060310"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:37
S88	436	S71 S72 S87	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:39
S89	88	((chip or die or ic or (integrated adj circuit) or semiconductor) and (via) and (trace or line or lead) and ((carrier or wafer or board or pcb) with (scribe or scribing or dice or dicing)) and (solder or bump) and ((cavity or void or opening or pocket) with (carrier or wafer))) and @pd>"20060310"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:40
S90	2233	((plurality or multiple or numerous) with (chip or die or ic or (integrated adj circuit) or semiconductor)) and (via) and (trace or line or lead) and ((carrier or wafer or board or pcb) with (scribe or scribing or dice or dicing)) and (solder or bump) and ((ceramic or silicone or glass or si or silicon or plastic) with (carrier or wafer or pcb or board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:40
S91	20	(S90 and (polimide or BCB)) and @pd>"20060310"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:40
S92	85	(S90 and (polyimide or BCB)) and @pd>"20060310"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/15 17:38

EAST Search History

S93	478	S88 S89 S92 S91	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:41
S94	233	S93 and (polyimide or BCB)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:58
S95	0	S94 not S93	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:59
S96	245	S93 not S94	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/04 18:59
S97	1	("7087991").PN.	US-PGPUB; USPAT	OR	OFF	2006/12/14 15:59